

Bonding Wire Customer Application Questionnaire



Form Rev Aug 24, 2015

Date	201	Position	[] Engine	eering [] Purchasing
Contact		Title		
Company		Tel		Ext
email		Project	Ref#	
Tanaka Se	eries [] Unknown []] Other		
] 4N Gold [] 2N Gold [] Silver [] Round [] Ribbon]AI-Si []AI []	Cu-Bare [] Pd coa	ited Cu [] Other
[]Ø15um	n []Ø18um []Ø20um []Ø25um []Ø.7mil []Ø.8mil []Ø1.0mil			
Applicatio	n:			[] Bonding
				[] Power
				[] RF
				[] Other
Die: []Si	i with Al pads [] Other			
Lead Fram	ne: [] Cu Alloy [] BT Substrate [] COB Other		
Bonding M	1ethod: [] Ball Bonding [] Wedge I	Bonding [] Other		
Spool Size	e: [] >2-inch [] Half-inc	ch only		
	[] ASM Pacific [] F&K Delvotec [] He			
	[] Orthodyne [] Palomar [] Sh			Bond [] Other
Model Nbr	enabled for copper wire ? [] Yes [
Quantity:	[] Minimum (one-spool)		Qty spools	[]Now []Future